

CLAIMS

1. A resin composition, comprising a filler,
a value four times the average particle diameter of
5 the filler being equal to or less than the thickness of the
resin composition,
wherein the thickness of the resin composition is 1000
micrometres (μm) or less,
wherein when the thickness of the resin composition is
10 regarded as 100%, a maximum particle diameter of the filler
is 5% to 67%, and
wherein the maximum particle diameter of the filler is
75 micrometres (μm) or less.
- 15 2. The resin composition according to claim 1, which
is in a sheet form.
3. A semiconductor device manufacturing method,
comprising the step of covering a semiconductor chip with
20 the resin composition recited in claim 1 or 2.
4. A semiconductor device, comprising:
a semiconductor chip; and
the resin composition recited in claim 1 or 2 covering
25 the semiconductor chip.